



Material Content Data Sheet



Sales Product Name		TLE6251DS		Issued		20. July 2018		
MA#		MA001464394						
Package		PG-DSO-8-16		Weight*		83.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.755	4.49	4.49	44890	44890
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8575	
wire	non noble metal	copper	7440-50-8	29.121	34.82	35.73	348172	357283
	noble metal	gold	7440-57-5	0.201	0.24	0.24	2399	2399
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.11		1117
encapsulation	plastics	epoxy resin	-	4.299	5.14		51401	
	inorganic material	silicondioxide	60676-86-0	42.337	50.62	55.87	506183	558701
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9730	9730
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7774	7774
glue	plastics	acrylic resin	-	0.354	0.42		4229	
	noble metal	silver	7440-22-4	1.254	1.50	1.92	14994	19223
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com